PNZ1270 Silicon NPN Phototransistor

For optical control systems

Features

- High sensitivity
- Good collector photo current linearity with respect to optical power input
- Fast response : $t_r = 2.5 \ \mu s$ (typ.)
- Small size designed for easier mounting to printed circuit board



Absolute Maximum Ratings (Ta = 25°C)

Parameter	Symbol	Ratings	Unit	
Collector to emitter voltage	V _{CEO}	20	V	
Emitter to collector voltage	V _{ECO}	5	V	
Collector current	I _C	20	mA	
Collector power dissipation	P _C	50	mW	
Operating ambient temperature	T _{opr}	-25 to +85	°C	
Storage temperature	T _{stg}	-30 to +100	°C	

Electro-Optical Characteristics ($Ta = 25^{\circ}C$)

Parameter	Symbol	Conditions	min	typ	max	Unit
Dark current	I _{CEO}	$V_{CE} = 10V$	l'all	1	100	nA
Collector photo current	I _{CE(L)} *3	$V_{CE} = 10V, L = 1000 lx^{*1}$	0.8		19.2	mA
Peak sensitivity wavelength	$\lambda_{\rm P}$	$V_{CE} = 10V$	5	800		nm
Acceptance half angle	θ	Measured from the optical axis to the half power point		14		deg.
Rise time	t _r *2	V = 10V I = 1mA P = 1000		2.5		μs
Fall time	t _f *2	$v_{CC} = 10v, \ I_{CE(L)} = 111A, \ R_L = 10022$		3.5		μs

*1 Measurements were made using a tungsten lamp (color temperature T = 2856K) as a light source.

*2 Switching time measurement circuit



 t_d : Delay time

- $t_r\colon$ Rise time (Time required for the collector photo current to increase from 10% to 90% of its final value)
- $t_{\rm f}\colon$ Fall time (Time required for the collector photo current to decrease from 90% to 10% of its initial value)

*3 I_{CE(L)} Classifications

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Class	Q	R	S	Т
I _{CE(L)} (mA)	0.8 to 2.4	1.6 to 4.8	3.2 to 9.6	6.4 to 19.2



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